

General Purpose Transistor PNP Silicon

MPS3906

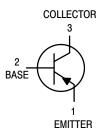
MAXIMUM RATINGS

Rating	Symbol	Value	Unit	
Collector–Emitter Voltage	V _{CEO}	-40	Vdc	
Collector-Base Voltage	V _{CBO}	-40	Vdc	
Emitter-Base Voltage	V _{EBO}	-5.0	Vdc	
Collector Current — Continuous	I _C	-200	mAdc	
Total Device Dissipation @ T _A = 25°C Derate above 25°C	P _D	625 5.0	mW mW/°C	
Total Device Dissipation @ T _C = 25°C Derate above 25°C	P _D	1.5 12	Watts mW/°C	
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-55 to +150	°C	



THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction to Case	$R_{ heta JC}$	83.3	°C/W



ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector–Emitter Breakdown Voltage ⁽¹⁾ $(I_C = -1.0 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	-40	_	Vdc
Collector–Base Breakdown Voltage ($I_C = -10 \mu Adc$, $I_E = 0$)	V _{(BR)CBO}	-40	_	Vdc
Emitter–Base Breakdown Voltage ($I_E = -10 \mu Adc$, $I_C = 0$)	V _{(BR)EBO}	-5.0	_	Vdc
Collector Cutoff Current (V _{CE} = -30 Vdc, V _{EB(off)} = -3.0 Vdc)	I _{CEX}	_	-50	nAdc
Base Cutoff Current $(V_{CE} = -30 \text{ Vdc}, V_{EB(off)} = -3.0 \text{ Vdc})$	I _{BL}	_	-50	nAdc

^{1.} Pulse Test: Pulse Width = 300 μ s; Duty Cycle = 2.0%.

MPS3906

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted) (Continued)

	Characteristic	Symbol	Min	Max	Unit
ON CHARACTERISTICS ⁽¹⁾					
DC Current Gain $ \begin{aligned} &(I_C = -0.1 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc)} \\ &(I_C = -1.0 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc)} \\ &(I_C = -10 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc)} \\ &(I_C = -50 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc)} \\ &(I_C = -100 \text{ mAdc, } V_{CE} = -1.0 \text{ Vdc)} \end{aligned} $			60 80 100 60 30	 300 	_
Collector–Emitter Saturation Voltage ($I_C = -10$ mAdc, $I_B = -1.0$ mAdc) ($I_C = -50$ mAdc, $I_B = -5.0$ mAdc)			_ _	-0.25 -0.4	Vdc
Base–Emitter Saturation Voltage ($I_C = -10$ mAdc, $I_B = -1.0$ mAdc) ($I_C = -50$ mAdc, $I_B = -5.0$ mAdc)			-0.65 	-0.85 -0.95	Vdc
SMALL-SIGNAL O	CHARACTERISTICS				
Current–Gain — Bar (I _C = –10 mAdc, V	f _T	250	_	MHz	
Output Capacitance (V _{CB} = -5.0 Vdc, I	_E = 0, f = 1.0 MHz)	C _{obo}	_	4.5	pF
Input Capacitance (V _{EB} = -0.5 Vdc, I _C = 0, f = 1.0 MHz)		C _{ibo}	_	10	pF
Input Impedance (I _C = -1.0 mAdc, \	/ _{CE} = −10 Vdc, f = 1.0 kHz)	h _{ie}	2.0	12	kΩ
Voltage Feedback R (I _C = -1.0 mAdc, \	atio / _{CE} = -10 Vdc, f = 1.0 kHz)	h _{re}	1.0	10	X 10 ⁻⁴
Small–Signal Current Gain (I _C = -1.0 mAdc, V _{CE} = -10 Vdc, f = 1.0 kHz)			100	400	_
Output Admittance ($I_C = -1.0 \text{ mAdc}$, $V_{CE} = -10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)			3.0	60	μmhos
Noise Figure (I _C = $-100 \mu Adc$, V _{CE} = $-5.0 Vdc$, R _S = $1.0 k \Omega$, f = $1.0 kHz$)			_	4.0	dB
SWITCHING CHAP	RACTERISTICS	<u>'</u>		1	
Delay Time	$(V_{CC} = -3.0 \text{ Vdc}, V_{BE(off)} = +0.5 \text{ Vdc},$	t _d	_	35	ns
Rise Time	$I_{\rm C} = -10 \text{ mAdc}, I_{\rm B1} = 1.0 \text{ mAdc})$	t _r	_	50	ns
Storage Time	$(V_{CC} = -3.0 \text{ Vdc}, I_{C} = -10 \text{ mAdc},$	t _s	_	600	ns
Fall Time $I_{B1} = I_{B2} = -1.0 \text{ mAdc}$		t _f	_	90	ns

^{1.} Pulse Test: Pulse Width = 300 μs; Duty Cycle = 2.0%.

TYPICAL NOISE CHARACTERISTICS

 $(V_{CE} = -5.0 \text{ Vdc}, T_A = 25^{\circ}\text{C})$

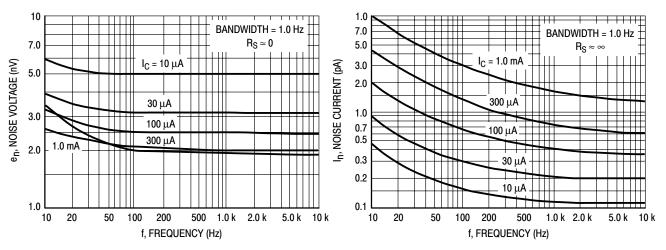


Figure 1. Noise Voltage

Figure 2. Noise Current

NOISE FIGURE CONTOURS

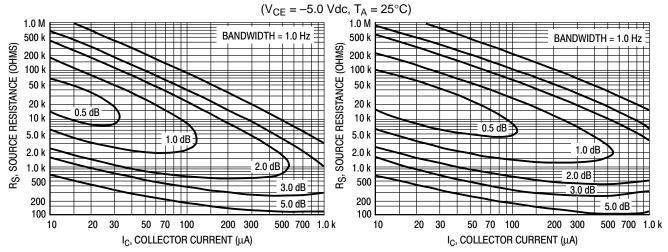


Figure 3. Narrow Band, 100 Hz

Figure 4. Narrow Band, 1.0 kHz

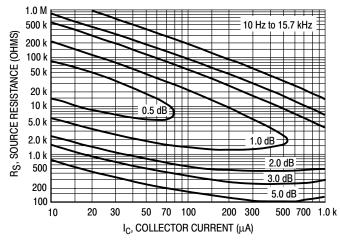


Figure 5. Wideband

Noise Figure is Defined as:

$$NF = 20 \log_{10} \left[\frac{e_0^2 + 4KTR_S + I_0^2 R_S^2}{4KTR_S} \right]^{1/2}$$

e_n = Noise Voltage of the Transistor referred to the input. (Figure 3)

I_n = Noise Current of the Transistor referred to the input. (Figure 4)

K = Boltzman's Constant (1.38 x 10^{-23} j/°K)

T = Temperature of the Source Resistance (°K)

R_S = Source Resistance (Ohms)

MPS3906

TYPICAL STATIC CHARACTERISTICS

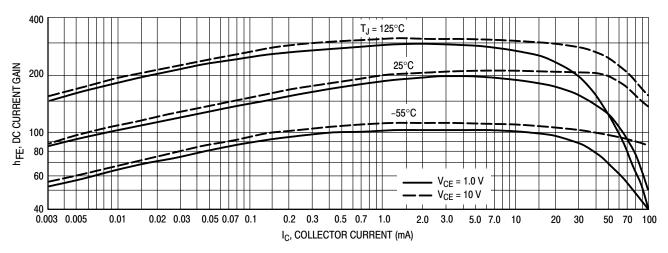


Figure 6. DC Current Gain

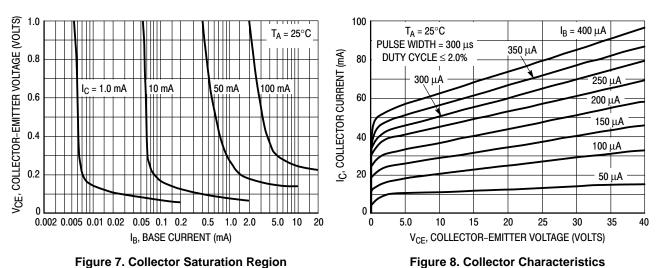


Figure 7. Collector Saturation Region

V, VOLTAGE (VOLTS)

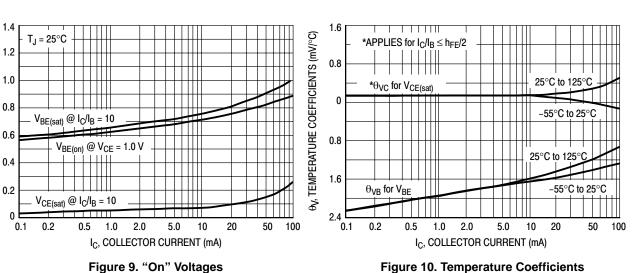
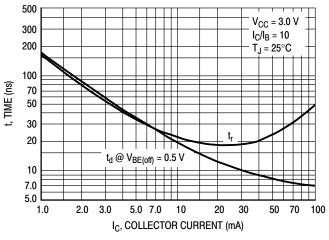


Figure 10. Temperature Coefficients

TYPICAL DYNAMIC CHARACTERISTICS



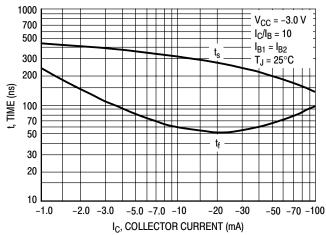
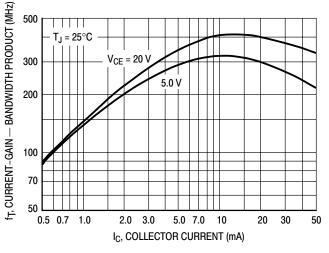


Figure 11. Turn-On Time

Figure 12. Turn-Off Time



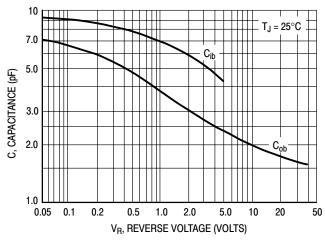
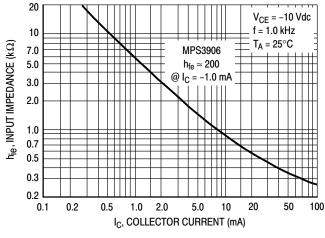


Figure 13. Current-Gain — Bandwidth Product

Figure 14. Capacitance



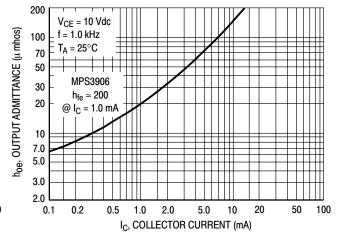


Figure 15. Input Impedance

Figure 16. Output Admittance

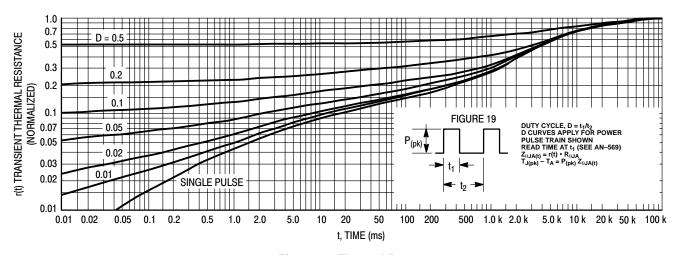
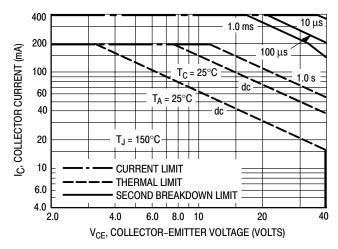


Figure 17. Thermal Response



The safe operating area curves indicate I_C – V_{CE} limits of the transistor that must be observed for reliable operation. Collector load lines for specific circuits must fall below the limits indicated by the applicable curve.

The data of Figure 18 is based upon $T_{J(pk)}=150^{\circ}C$; T_{C} or T_{A} is variable depending upon conditions. Pulse curves are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^{\circ}C$. $T_{J(pk)}$ may be calculated from the data in Figure 17. At high case or ambient temperatures, thermal limitations will reduce the power than can be handled to values less than the limitations imposed by second breakdown.

Figure 18. Active-Region Safe Operating Area

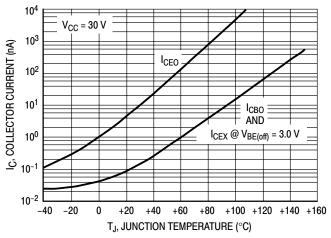


Figure 19. Typical Collector Leakage Current

DESIGN NOTE: USE OF THERMAL RESPONSE DATA

A train of periodical power pulses can be represented by the model as shown in Figure 19. Using the model and the device thermal response the normalized effective transient thermal resistance of Figure 17 was calculated for various duty cycles.

To find $Z_{\theta JA(t)},$ multiply the value obtained from Figure 17 by the steady state value $R_{\theta JA}.$

Example:

Dissipating 2.0 watts peak under the following conditions:

 $t_1 = 1.0 \text{ ms}, t_2 = 5.0 \text{ ms} (D = 0.2)$

Using Figure 17 at a pulse width of 1.0 ms and D = 0.2, the reading of r(t) is 0.22.

The peak rise in junction temperature is therefore

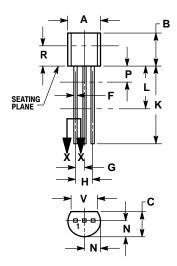
 $\Delta T = r(t) \times P_{(pk)} \times R_{\theta JA} = 0.22 \times 2.0 \times 200 = 88^{\circ}C.$

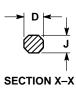
For more information, see AN-569.

MPS3906

PACKAGE DIMENSIONS

CASE 029-04 (TO-226AA) ISSUE AD





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
 4. DIMENSION F APPLIES BETWEEN P AND L. DIMENSION D AND J APPLY BETWEEN L AND K MINIMUM. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.022	0.41	0.55
F	0.016	0.019	0.41	0.48
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
P		0.100	-	2.54
R	0.115		2.93	
V	0.135		3.43	

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